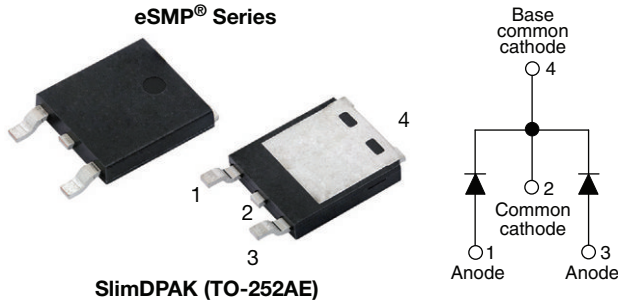


## Hyper Fast Rectifier, 2 x 4 A FRED Pt<sup>®</sup>



### FEATURES

- Hyperfast recovery time
- 175 °C max. operating junction temperature
- Low forward voltage drop reduced  $Q_{rr}$  and soft recovery
- Low leakage current
- Very low profile - typical height of 1.3 mm
- Polyimide passivation for high reliability standard
- Ideal for automated placement
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C
- Meets JESD 201 class 2 whisker test
- Material categorization: for definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)



**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**

### LINKS TO ADDITIONAL RESOURCES



3D Models

PRIMARY CHARACTERISTICS	
$I_{F(AV)}$	2 x 4 A
$V_R$	100 V
$V_F$ at $I_F$	0.71 V
$t_{rr}$ (typ.)	16 ns
$T_J$ max.	175 °C
Package	SlimDPAK (TO-252AE)
Circuit configuration	Common cathode

### DESCRIPTION / APPLICATIONS

State of the art hyperfast recovery rectifiers designed with optimized performance of forward voltage drop, hyperfast recovery time, and soft recovery.

The planar structure and the platinum doped life time control guarantee the best overall performance, ruggedness and reliability characteristics.

These devices are intended for use in PFC boost stage in the AC/DC section of SMPS inverters or as freewheeling diodes. Their extremely optimized stored charge and low recovery current minimize the switching losses and reduce over dissipation in the switching element and snubbers.

### MECHANICAL DATA

**Case:** SlimDPAK (TO-252AE)

Molding compound meets UL 94 V-0 flammability rating  
Halogen-free, RoHS-compliant

**Terminals:** matte tin plated leads, solderable per J-STD-002

ABSOLUTE MAXIMUM RATINGS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Peak repetitive reverse voltage	$V_{RRM}$		100	V
Average rectified forward current per leg per device	$I_{F(AV)}$	$T_C = 167\text{ °C}$	4 8	A
Non-repetitive peak surge current per leg	$I_{FSM}$	$T_J = 25\text{ °C}$ , 10 ms sine pulse wave	100	
Operating junction and storage temperatures	$T_J, T_{Stg}$		-55 to +175	°C

ELECTRICAL SPECIFICATIONS ( $T_J = 25\text{ °C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Breakdown voltage, blocking voltage	$V_{BR}, V_R$	$I_R = 100\text{ }\mu\text{A}$	100	-	-	V
Forward voltage per leg	$V_F$	$I_F = 4\text{ A}$	-	0.88	1.0	
		$I_F = 8\text{ A}$	-	0.97	1.14	
		$I_F = 4\text{ A}, T_J = 150\text{ °C}$	-	0.71	0.80	
Reverse leakage current per leg	$I_R$	$V_R = V_R$ rated	-	-	4	$\mu\text{A}$
		$T_J = 150\text{ °C}, V_R = V_R$ rated	-	-	80	
Junction capacitance per leg	$C_T$	$V_R = 100\text{ V}$	-	17	-	pF

<b>DYNAMIC RECOVERY CHARACTERISTICS</b> ( $T_J = 25\text{ }^\circ\text{C}$ unless otherwise specified)						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Reverse recovery time	$t_{rr}$	$I_F = 1\text{ A}$ , $di_F/dt = 100\text{ A}/\mu\text{s}$ , $V_R = 30\text{ V}$	-	16	-	ns
		$I_F = 0.5\text{ A}$ , $I_R = 1\text{ A}$ , $I_{RR} = 0.25\text{ A}$	-	-	25	
		$T_J = 25\text{ }^\circ\text{C}$	-	20	-	
		$T_J = 125\text{ }^\circ\text{C}$	-	30	-	
Peak recovery current	$I_{RRM}$	$T_J = 25\text{ }^\circ\text{C}$	-	2.5	-	A
		$T_J = 125\text{ }^\circ\text{C}$	-	4	-	
Reverse recovery charge	$Q_{rr}$	$T_J = 25\text{ }^\circ\text{C}$	-	25	-	nC
		$T_J = 125\text{ }^\circ\text{C}$	-	60	-	

<b>THERMAL - MECHANICAL SPECIFICATIONS</b>						
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNITS
Maximum junction and storage temperature range	$T_J$ , $T_{Stg}$		-55	-	175	$^\circ\text{C}$
Thermal resistance, junction to ambient per diode	$R_{thJA}$ (1)(2)		-	73	90	$^\circ\text{C}/\text{W}$
Thermal resistance, junction to mount per diode	$R_{thJM}$ (3)		-	2.1	2.5	$^\circ\text{C}/\text{W}$
Weight			-	0.20	-	g
Marking device		Case style SlimDPAK (TO-252AE)	8CVH01			

**Notes**

- (1) The heat generated must be less than thermal conductivity from junction to ambient;  $dP_D/dT_J < 1 R_{thJA}$
- (2) Free air, mounted or recommended copper pad area; thermal resistance  $R_{thJA}$  - junction to ambient
- (3) Mounted on infinite heatsink

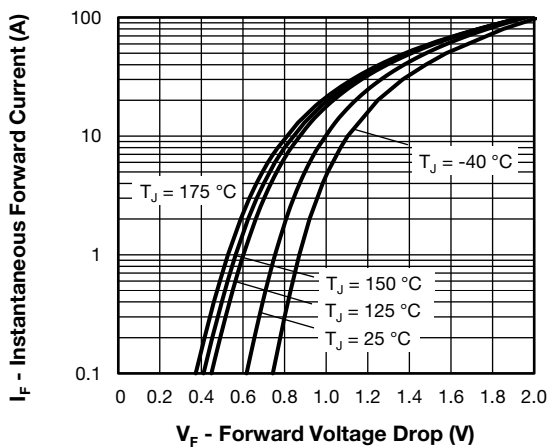


Fig. 1 - Typical Forward Voltage Drop Characteristics

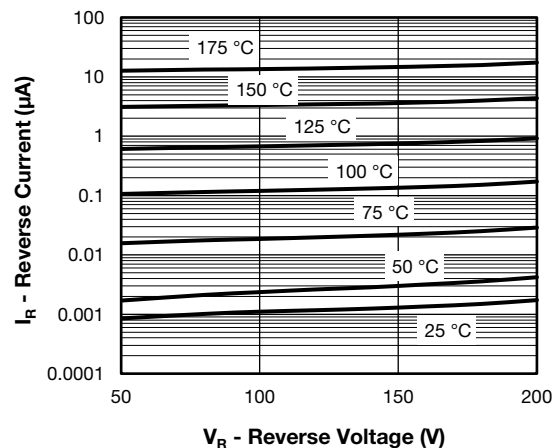


Fig. 2 - Typical Values of Reverse Current vs. Reverse Voltage

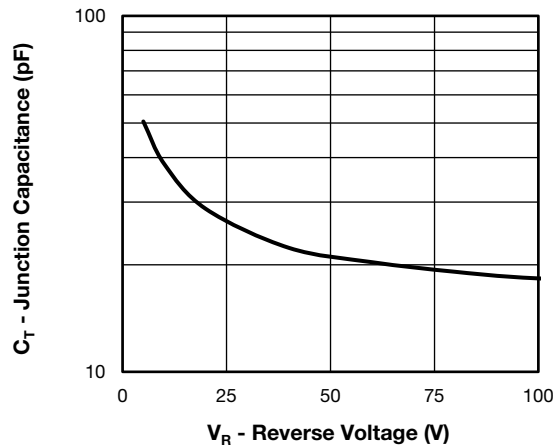


Fig. 3 - Typical Junction Capacitance vs. Reverse Voltage

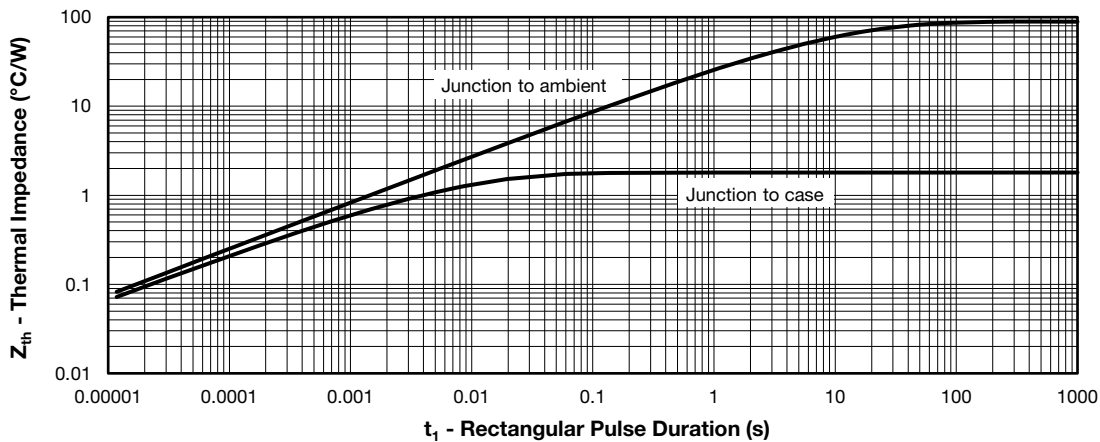


Fig. 4 - Maximum Thermal Impedance  $Z_{thJC}$  Characteristics

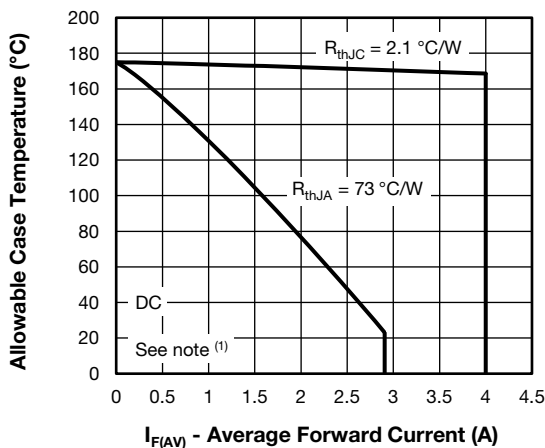


Fig. 5 - Maximum Allowable Case Temperature vs. Average Forward Current

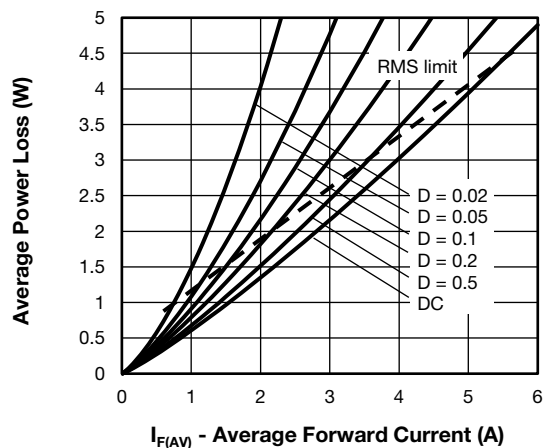


Fig. 6 - Forward Power Loss Characteristics

**Note**

- (1) Formula used:  $T_C = T_J - (P_d + P_{dREV}) \times R_{thJC}$ ;
- $P_d$  = forward power loss =  $I_{F(AV)} \times V_{FM}$  at  $(I_{F(AV)}/D)$  (see fig. 6);
- $P_{dREV}$  = inverse power loss =  $V_{R1} \times I_R (1 - D)$ ;  $I_R$  at  $V_{R1}$  = rated  $V_R$

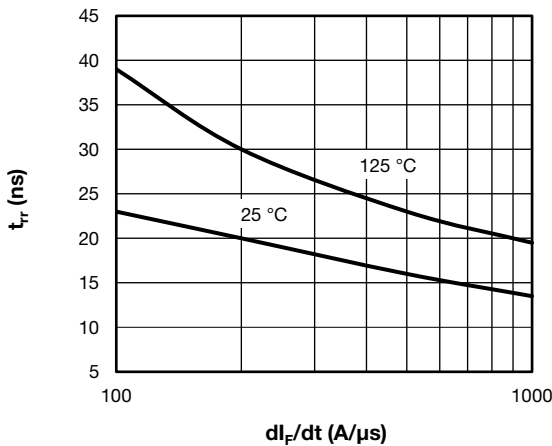


Fig. 7 - Typical Reverse Recovery Time vs.  $di_F/dt$

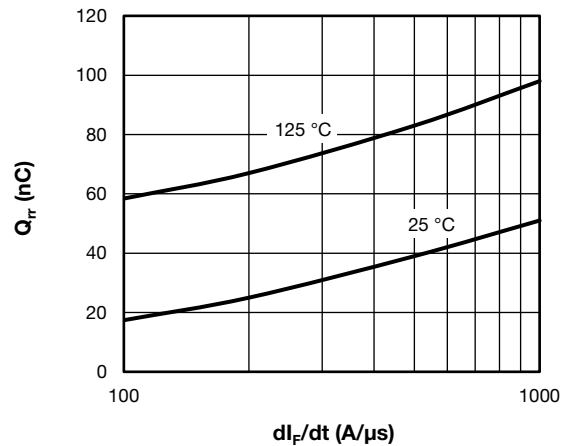
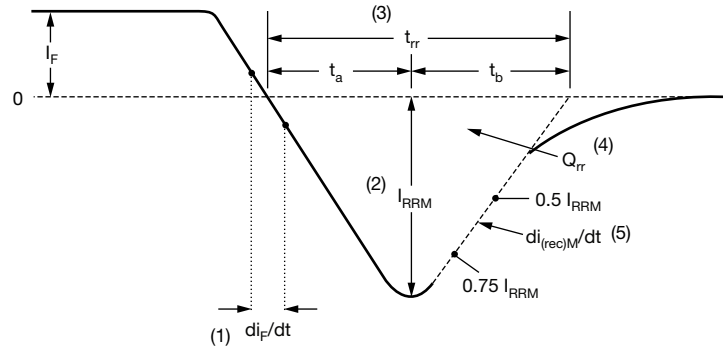


Fig. 8 - Typical Stored Charge vs.  $di_F/dt$



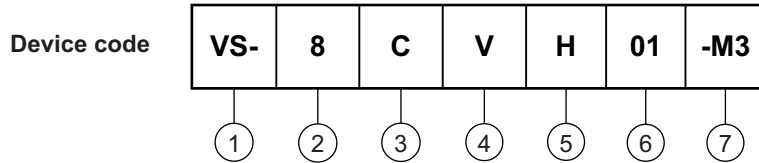
- (1)  $di_F/dt$  - rate of change of current through zero crossing
- (2)  $I_{RRM}$  - peak reverse recovery current
- (3)  $t_{rr}$  - reverse recovery time measured from zero crossing point of negative going  $I_F$  to point where a line passing through  $0.75 I_{RRM}$  and  $0.50 I_{RRM}$  extrapolated to zero current.
- (4)  $Q_{rr}$  - area under curve defined by  $t_{rr}$  and  $I_{RRM}$
- (5)  $di_{(rec)M}/dt$  - peak rate of change of current during  $t_b$  portion of  $t_{rr}$

$$Q_{rr} = \frac{t_{rr} \times I_{RRM}}{2}$$

Fig. 9 - Reverse Recovery Waveform and Definitions



ORDERING INFORMATION TABLE



- 1** - Vishay Semiconductors product
- 2** - Current rating (8 = 8 A)
- 3** - Circuit configuration:  
C = common cathode
- 4** - V = SlimDPAK
- 5** - Process type,  
H = hyperfast recovery
- 6** - Voltage code (01 = 100 V)
- 7** - -M3 = halogen-free, RoHS-compliant, and terminations lead (Pb)-free

ORDERING INFORMATION (Example)			
PREFERRED P/N	QUANTITY PER REEL	MINIMUM ORDER QUANTITY	PACKAGING DESCRIPTION
VS-8CVH01-M3/I	4500	4500	13" diameter plastic tape and reel

LINKS TO RELATED DOCUMENTS	
Dimensions	<a href="http://www.vishay.com/doc?96081">www.vishay.com/doc?96081</a>
Part marking information	<a href="http://www.vishay.com/doc?96085">www.vishay.com/doc?96085</a>
Packaging information	<a href="http://www.vishay.com/doc?88869">www.vishay.com/doc?88869</a>
SPICE model	<a href="http://www.vishay.com/doc?97122">www.vishay.com/doc?97122</a>



### SlimDPAK

**DIMENSIONS** in inches (millimeters)



### Mounting Pad Layout





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